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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/853,233	05/11/2001	Steven T. Harshfield	MICS:0061	5984	
759	90 09/04/2002				
Michael G. Fletcher Fletcher, Yoder & Van Someren P.O. Box 692289 Houston, TX 77269-2289			EXAMINER		
			COLEMAN, WILLIAM D		
			ART UNIT	PAPER NUMBER	
			2823	14	
			DATE MAILED: 09/04/2002		

Please find below and/or attached an Office communication concerning this application or proceeding.

, J		Application N	,	Applicant(a)	
				Applicant(s)	
	Offic Action Summary	09/853,233		HARSHFIELD ET AL.	
	Onic Action Summary	Examiner	_	Art Unit	
	The MAN INC DATE - SAL'-	W. David Cole		2823	
Period fo	• •				
THE I - External form - If the - If NO - Failur - Any r	ORTENED STATUTORY PERIOD FOR R MAILING DATE OF THIS COMMUNICATI nsions of time may be available under the provisions of 37 C SIX (6) MONTHS from the mailing date of this communicating period for reply specified above is less than thirty (30) days a period for reply is specified above, the maximum statutory into the reply within the set or extended period for reply will, by eply received by the Office later than three months after the edipatent term adjustment. See 37 CFR 1.704(b).	ON. FR 1.136(a). In no event, ho on. , a reply within the statutory r period will apply and will expl statute. cause the application	wever, may a reply be the name of thirty (30) do to SIX (6) MONTHS from the Decome ARANDON	timely filed ays will be considered timely. m the mailing date of this communication.	
1)⊠	Responsive to communication(s) filed or	n 31 July 2002 .			
2a) <u></u> □		This action is non-	final.		
3)□ Dispositi	Since this application is in condition for a closed in accordance with the practice u on of Claims	allowance except for	formal matters, p	prosecution as to the merits is 453 O.G. 213.	
4)⊠	Claim(s) 1-44 is/are pending in the applic	ation.			
	4a) Of the above claim(s) is/are wit	hdrawn from conside	eration.		
5)🖂	Claim(s) 8-16 is/are allowed.				
6)⊠	Claim(s) <u>1-3,5,7,17-19,21,23,26,28,31-33</u>	, <u>35,38-40 and 42</u> is/	are rejected.		
	Claim(s) 4,6,20,22,24,25,27,29,30,34,36,		•		
	Claim(s) are subject to restriction a		•		
	on Papers	·			
9) 🗌 -	The specification is objected to by the Exa	miner.			
10) 🔲 🗂	Γhe drawing(s) filed on is/are: a)□	accepted or b) obje	cted to by the Exa	aminer.	
	Applicant may not request that any objection	to the drawing(s) be h	eld in abeyance. S	See 37 CFR 1.85(a).	
11) 🔲 🗆	The proposed drawing correction filed on _	is: a) 🔲 appro	/ed b)∐ disappr	oved by the Examiner.	
	If approved, corrected drawings are required		ction.		
12) 🔲 🛚	The oath or declaration is objected to by th	e Examiner.			
Priority u	nder 35 U.S.C. §§ 119 and 120				
13)	Acknowledgment is made of a claim for fo	reign priority under :	35 U.S.C. § 119(a)-(d) or (f).	
a)[☐ All b)☐ Some * c)☐ None of:				
	1. Certified copies of the priority docur	ments have been red	eived.		
	2. Certified copies of the priority docur	ments have been red	eived in Applica	tion No	
* S	3. Copies of the certified copies of the application from the Internation ee the attached detailed Office action for a	al Bureau (PCT Rule	17.2(a)).	•	
	cknowledgment is made of a claim for dor		•		
a	☐ The translation of the foreign languag cknowledgment is made of a claim for do	e provisional applica	tion has been re	ceived.	
Attachment	(s)				
2) Notice	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-94) nation Disclosure Statement(s) (PTO-1449) Paper N		Notice of Informat	ry (PTO-413) Paper No(s) Patent Application (PTO-152)	
S. Patent and Tr PTO-326 (Rev		ic Action Summary		Part of Paper No. 4	



DETAILED ACTION

1. Applicant's election without traverse of group I invention, claims 1-44 in Paper No. 3 is acknowledged.

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in-
- (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effect under this subsection of a national application published under section 122(b) only if the international application designating the United States was published under Article 21(2)(a) of such treaty in the English language; or
- (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that a patent shall not be deemed filed in the United States for the purposes of this subsection based on the filing of an international application filed under the treaty defined in section 351(a).
- 3. Claims 1, 2, 3, 5, 21, 23, 26, 28, 31, 32, 33, 35, 38, 39, 40 and 42 are rejected under 35 U.S.C. 102(e) as being anticipated by Sandhu, U.S. Patent 6,392,913 B1.
- 4. <u>Sandhu</u> discloses a semiconductor device as claimed. See **FIG. 4**.
- 5. Pertaining to claim 1, <u>Sandhu</u> teaches a memory cell comprising:
- a first line 14 formed over a substrate, the first line being formed of a first conductive material;
- a layer of a second conductive material 42 disposed over the first line, the second conductive

material being different from the first conductive material (shading is different for each material);

a layer of chalcogenide material 44 disposed over the layer of the second conductive material; and



a second line 48 formed over the layer of chalcogenide material.

- 6. Pertaining to claims 2 and 32, <u>Sandhu</u> teaches the memory cell, as set forth in claim 1, wherein the first line is embedded in the substrate.
- 7. Pertaining to claims 3 and 33, <u>Sandhu</u> teaches the memory cell, as set forth in claim 1, wherein the first line is disposed in a window formed in a dielectric layer **16** disposed over the substrate.
- 8. Pertaining to claim 5, <u>Sandhu</u> teaches the memory cell, as set forth in claim 1, wherein the layer of a second conductive material is deposited on the first line using an immersion plating technique (please note that there is no patentable weight given to the process since these are product by process claims and only the product will be examined).
- 9. Pertaining to claim 17, <u>Sandhu</u> teaches the memory cell, as set forth in claim 1, wherein the first line is embedded in the substrate.
- 10. Pertaining to claim 18, Sandhu teaches the memory cell, as set forth in claim 1, wherein the first line is disposed in a window formed in a dielectric layer disposed over the substrate.
- 11. Pertaining to claim 21, <u>Sandhu</u> teaches a memory cell comprising:
 - a first layer of dielectric material disposed over a substrate, the first layer of dielectric material having a first window therein;
 - a first line disposed in the first window, the first line being formed of a first conductive material;
 - a second layer of dielectric material disposed over the first layer of dielectric material and over the first line, the second layer of dielectric material having a second window therein, the second window exposing at least a portion of the first line;



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layer of a second conductive material disposed in the second window over the first line, the second conductive material being different from the first conductive material;

layer of chalcogenide material disposed in the second window over the layer of the second conductive material; and second line formed over the layer of chalcogenide material.

12. Pertaining to claim 23, <u>Sandhu</u> teaches the memory cell, as set forth in claim 2 1, wherein the layer of a second

conductive material is deposited on the first line using an immersion plating technique.

13. Pertaining to claim 26, <u>Sandhu</u> teaches a memory cell comprising:

a first layer of dielectric material disposed over a substrate, the first layer of dielectric material having a first window therein; a first line disposed in the first window, the first line being formed of a first conductive material;

a second layer of dielectric material disposed over the first layer of dielectric material and over the first line;

first layer of conductive material disposed over the second layer of dielectric material, the first layer of conductive material and the second layer of dielectric material having a second window therein, the second window exposing at least a portion of the first line;

a layer of a second conductive material disposed in the second window over the first line, the second conductive material being different from the first conductive material;

a layer of chalcogenide material disposed in the second window over the layer of the second conductive material; and



a second line formed over the layer of chalcogenide material and over the first layer of conductive material.

14. Pertaining to claim 28, <u>Sandhu</u> teaches the memory cell, as set forth in claim 26, wherein the layer of a second

conductive material is deposited on the first line using an immersion plating technique.

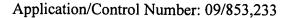
Pertaining to claim 31, Sandhu teaches a memory comprising:

- a memory array having a plurality of memory cells, each of the memory cells comprising:
- a first line formed over a substrate, the first line being formed of a first conductive

material; a layer of a second conductive material disposed over the first line, the second

conductive material being different from the first conductive material;

- a layer of chalcogenide disposed over the layer of the second conductive material;
- and a second line formed over the layer of chalcogenide.
- 15. Pertaining to claim 32, <u>Sandhu</u> teaches the memory cell, as set forth in claim 3 1, wherein the first line is embedded in the substrate.
- 16. Pertaining to claim 33, <u>Sandhu</u> teaches the memory cell, as set forth in claim 31, wherein the first line is disposed in a window formed in a dielectric layer disposed over the substrate.
- 17. Pertaining to claim 35, <u>Sandhu</u> teaches the memory cell, as set forth in claim 31, wherein the layer of a second conductive material is deposited on the first line using an immersion plating technique.
- 18. Pertaining to claim 38, Sandhu teaches an electronic device comprising:
- a processor; a memory operatively coupled to the processor, the memory comprising a memory array having a plurality of memory cells, each of the memory cells comprising:



a first line formed over a substrate, the first line being formed of a first conductive material; a layer of a second conductive material disposed over the first line, the second conductive material being different from the first conductive material;

- a layer of chalcogenide disposed over the layer of the second conductive material; and a second line formed over the layer of chalcogenide.
- 19. Pertaining to claim 39, <u>Sandhu</u> teaches the memory cell, as set forth in claim 38, wherein the first line is embedded in the substrate.
- 20. Pertaining to claim 40, <u>Sandhu</u> teaches the memory cell, as set forth in claim 38, wherein the first line is disposed in a window formed in a dielectric layer disposed over the substrate.
- 21. Pertaining to claim 42, <u>Sandhu</u> teaches the memory cell, as set forth in claim 38, wherein the layer of a second conductive material is deposited on the first line using an immersion plating.

Objections

- 22. Claims 2 and 17 are objected to under 37 CFR 1.75 as being a substantial duplicate of each other. When two claims in an application are duplicates or else are so close in content that they both cover the same thing, despite a slight difference in wording, it is proper after allowing one claim to object to the other as being a substantial duplicate of the allowed claim. See MPEP § 706.03(k).
- 23. Claims 4,6, 20, 22, 24, 25, 27, 29, 30,34, 36, 37, 41, 43 and 44 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

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Allowable Subject Matter

- 24. Claims 8-15 allowed.
- 25. The following is an examiner's statement of reasons for allowance: prior art is not anticipated nor obvious as to a memory cell wherein a first line is disposed over a substrate and being a first metal, a layer of conductive material disposed over the first line wherein the layer of conductive material being formed of a second metal and being more noble than the first metal.
- 26. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

27. Any inquiry concerning this communication or earlier communications from the examiner should be directed to W. David Coleman whose telephone number is 703-305-0004. The examiner can normally be reached on 9:00 AM-5:00 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael M. Fahmy can be reached on 703-308-4918. The fax phone numbers for the organization where this application or proceeding is assigned are 703-308-7722 for regular communications and 703-308-7721 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

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W. David Coleman Examiner Art Unit 2823

WDC August 25, 2002

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